

Features

- Super small volume, large current.
- Ultra-thin silicon wafer manufacturing, protection technology.
- Thin ceramic package or encapsulation without ceramic package.
- Special multilayer metal ohmic contact.
- High-power avalanche features.
- Large surge current test.
- R_F Can be directly connected in parallel with ultra-low threshold voltage VFO, low slope resistor R_F .
- $R_{th(j-c)}$ Low junction case thermal resistance $R_{th(j-c)}$.
- Used for reduced volume and great increase current.



Ceramic package

Type	$I_{F(AV)}@T_c$ =85℃	VRRM	$I_{FSM}@T_{jm}$ &10ms	$V_{FM}@I_{FM}$ & $T_c=25℃$		V_{FO} @ T_{jm}	r_F @ T_{jm}	Q_{rr}	T_{jm}	$R_{th(j-c)}$	压装力F ±10%	外形尺寸
	A	V	kA	V	A	V	mΩ	μC	℃	K/W	KN	
ZHA7100	7100	200~600	50	1.05	5000	0.74	0.025	≤400	175	0.010	30	ZTA50
ZHA12000	12000	200~600	85	1.02	8000	0.75	0.019	≤400	175	0.006	50	ZTA63
ZHA16000	16000	200~600	120	1.09	12000	0.75	0.017	≤400	175	0.004	70	ZTA76

Pressure package without case

Type	$I_{F(AV)}@T_c$ =85℃	VRRM	$I_{FSM}@T_{jm}$ &10ms	$V_{FM}@I_{FM}$ & $T_c=25℃$		V_{FO} @ T_{jm}	r_F @ T_{jm}	Q_{rr}	T_{jm}	$R_{th(j-c)}$	压装力F ±10%	外形尺寸
	A	V	kA	V	A	V	mΩ	μC	℃	K/W	KN	
ZHA9200	9200	200~600	60	1.03	2=8000	0.78	0.031	≤300	175	0.0056	33	ZTA53
ZHA10500	10500	200~600	70	1.01	8000	0.81	0.026	≤300	175	0.005	38	ZTA56
ZHA13500	13500	200~600	85	0.97	10000	0.76	0.021	≤300	175	0.004	50	ZTA63
ZHA18000	18000	200~600	135	1.09	12000	0.78	0.018	≤300	175	0.003	70	ZTA75